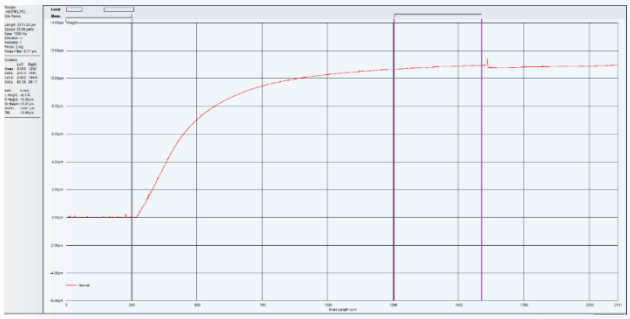
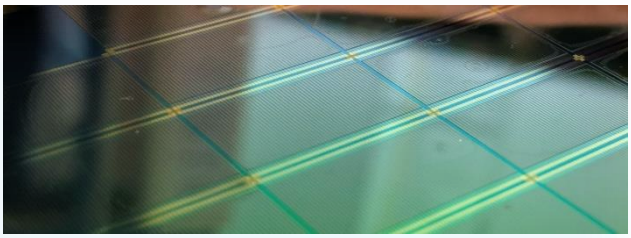
PARTNER PRESENTATION AND INTEREST IN HORIZON EUROPE PARTICIPATION

Implantable devices

Moore4Medical is addressing two important missing aspects: the development of a technology platform to efficiently deliver energy to the implants, and the **selective stimulation of peripheral nerves**.



Step height measurement for IMT structures using Tencor P-7 stylus profiler

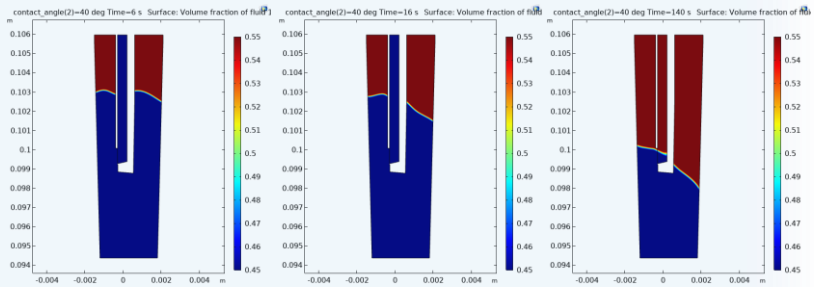


IMT structures with PI coating after dry etching process

The results from the encapsulation process of the electrodes fabricated at IMT, using spin coating technique are presented. The profilometer measurements for the IMT wafers showed a thickness of app 10 microns for the polyimide used in our experiments, deposited layers being uniform and compliant with the process specifications. The measurements show that our polyimide has a very good degree of coverage although it is deposited in thicker and uniform layers, which suits the thickness demand for acoustic attenuation measurements.

Microfluidics for Organ-on-Chip applications

In organ-on-chip (OoC) devices, the basic function of an organ is replicated in its simplest form in a chip comprising microfluidics, sensors and cells. In Moore4Medical, a "**smart well plate and lid**" platform will be developed, which provides the fluidic and electronic infrastructure to bring the individual OoC devices manufactured by start-ups and SMEs into the standard well plate format used in biological research and the pharmaceutical industry.



IMT is performing optimisation through simulation for various components of the Organ-on-Chip device. Modelling of the sample extraction from the well phenomena is presented (right - tip and well model; below – two phase flow simulations).

https://moore4medical.eu/

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TEL./E-MAIL:
+31-6-3898-1344
erik.vander.zeijden@philips.com

ECSEL JU

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